

21st International Conference on Electronic Commerce **(ICEC 2019)** **Busan, Korea, July 3-5, 2019**



CALL FOR PAPERS

The 21st International Conference on Electronic Commerce (ICEC 2019) will be held in Busan, Korea, on July 3-5, 2019. ICEC 2019 aims at providing researchers and practitioners in electronic commerce and related areas with an opportunity to present original ideas and share insightful opinions. The theme of ICEC 2019 is “**FinTech and Logistics in the Fourth Industrial Revolution Era.**”

We welcome submissions of original research papers addressing issues concerning the theory, design, development, evaluation, and application of electronic commerce and related fields. We also encourage submissions of research-in-progress contributions that are innovative and inspirational. Research articles particularly sought after are those motivated by real-world business problems and validated using rigorous research methodologies. For more information and program updates, please visit <http://icec.net>.

[Publication Policy] We encourage authors to submit full papers or extended abstracts of research-in-progress, however since 2018, we will publish only the abstract without making formal conference proceedings to leave the author’s copyright of publishing the papers in the international journals. Past ICEC proceedings can be found at www.ACM.org.

The submitted papers will be the base of selecting the best papers and invitation to special issue of the journals such [Electronic Commerce Research \(SSCI\)](#), [Electronic Commerce Research and Application \(SSCI\)](#), [Transportation Research-Part E: Logistics and Transportation Review \(SSCI\)](#), [Sustainability \(SSCI\)](#), [Information Technology for Development \(SSCI\)](#), [APJIS \(Scopus\)](#). If a paper is invited to the special issue of the above journals ICEC2019, then a revised paper will be submitted to the guest editors, where it will undergo a second-round review. The presentation at ICEC2019 will be not only a good channel to publication, but also a good opportunity to get constructive comments for the authors to further develop work-in-progress research. Relevant topics include, but are not limited to, the following:

- Fintech
- e-commerce in Asia Pacific
- Cross-border e-commerce
- Logistics
- Smart Factory and Manufacturing
- Mobile and Social Commerce

- AI in Accounting, Banking, and Finance
- Internet-of-Things for Business
- AI for e-Commerce and Wellness
- Big Data and Machine Learning in e-Commerce
- Smart Connected Services
- Entertainment, Virtual Reality and Augmented Reality
- Smart Connected Products and Services
- Smart and Wearable Technologies
- Cloud Services and Service Innovation
- Edge Computing
- Cobots and Logistics
- Block Chain, Cryptocurrency, and Token Economy
- AI in Marketing and Sales
- Social Media and Social Networking
- Emerging Financial Technology (Fintech)
- Smart Health & Hospitals
- Smart Tourism and Smart Logistics
- AI for Business Communication
- Bright Internet and Cybersecurity
- Education in Cyberspace
- Online-to-offline Services in e-Commerce
- Digital Twin
- Immersive Experience
- Event-Based Models
- Decentralized/Peer-to-Peer e-Commerce
- Chatbot and Conversational Agents

PAPER SUBMISSION

1. The Submitted papers must be original work. A paper with substantial overlap with the submission must neither be already published, nor be currently under review for publication in any other venue.

2. All submissions will be handled at <https://easychair.org/conferences/?conf=icec2019> that can be accessed through www.ICEC.net.

The official ACM Proceedings format is available as a template in Word format ([pubform ICEC2019.docx](#)). If you cannot reach the link of the template, please, [click](#) here for Baidu Cloud.

3. All submissions must be in English. Each paper is limited to 8 pages including figures and references. Please download the Manuscript Templates for Conference from the conference website: www.ICEC.net.

4. Both full papers and abstracts are welcome.

IMPORTANT DATES

Deadline for paper submission: ~~Feb 28, 2019~~ -> Mar 31, 2019

Notification of acceptance: ~~April 1, 2019~~ -> April 15, 2019

Deadline for final camera-ready version of accepted papers: ~~May 1, 2019~~ -> May 30, 2019

Conference Venue

The conference will be held in Haeundae Grand Hotel located at Haeundae beach, which is often considered one of the Korea's most famous and beautiful beaches.



Address: Haeundae-Beach Road 217, Haeundae-gu, Busan, Republic of Korea

Tel. +82 (0)51 7400 114, www.haeundaegrandhotel.com

Hosted by

International Center for Electronic Commerce (ICEC, <https://icec.net>)

Pusan National University Institute of China Studies (PNUICS, <https://pnuchinese.pusan.ac.kr>)

Conference Chairs: **Hyung Rim Choi**, Dong-A University (hrchoi@dau.ac.kr), Korea
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* July 3 – 4, 2019: Plenary and technical paper sessions.

* July 5 2019: Industry tour program.